

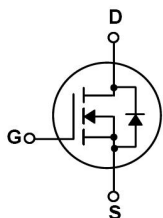
/ Descriptions

/ Features

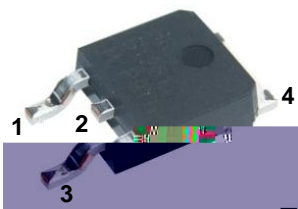
/ Applications

DC/DC

/ Equivalent Circuit

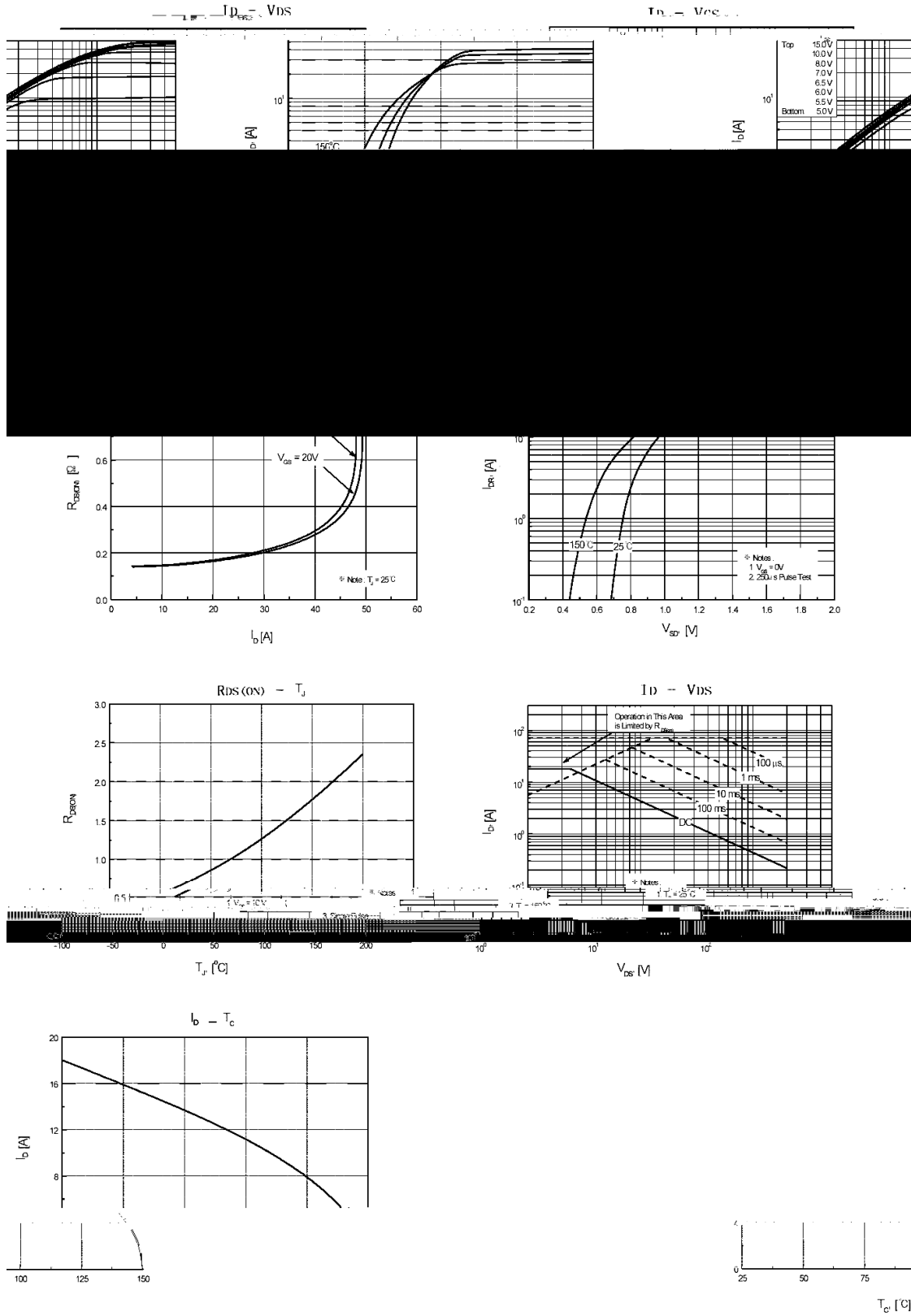


/ Pinning

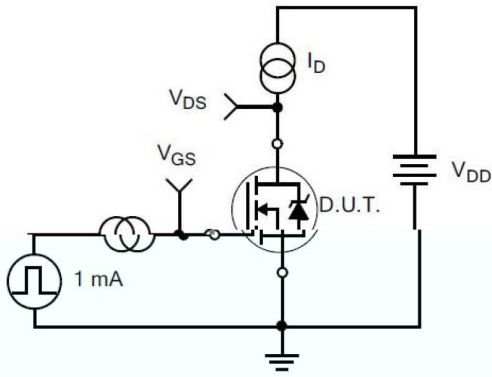


/ h_{FE} Classifications & Marking

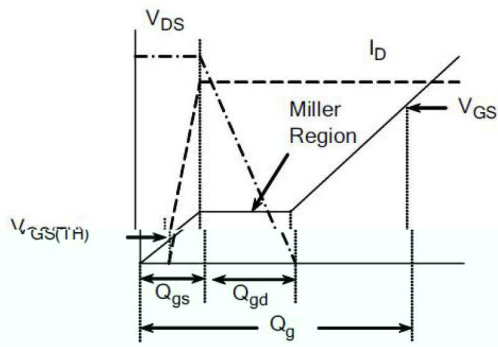
/ Electrical Characteristic Curve



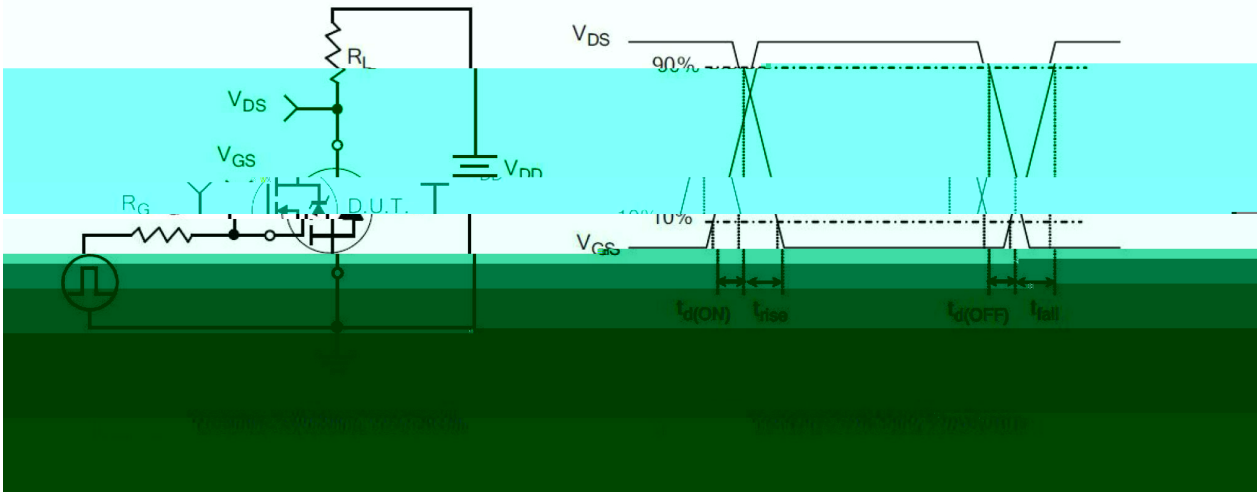
/ Test Circuit and Waveform Curve



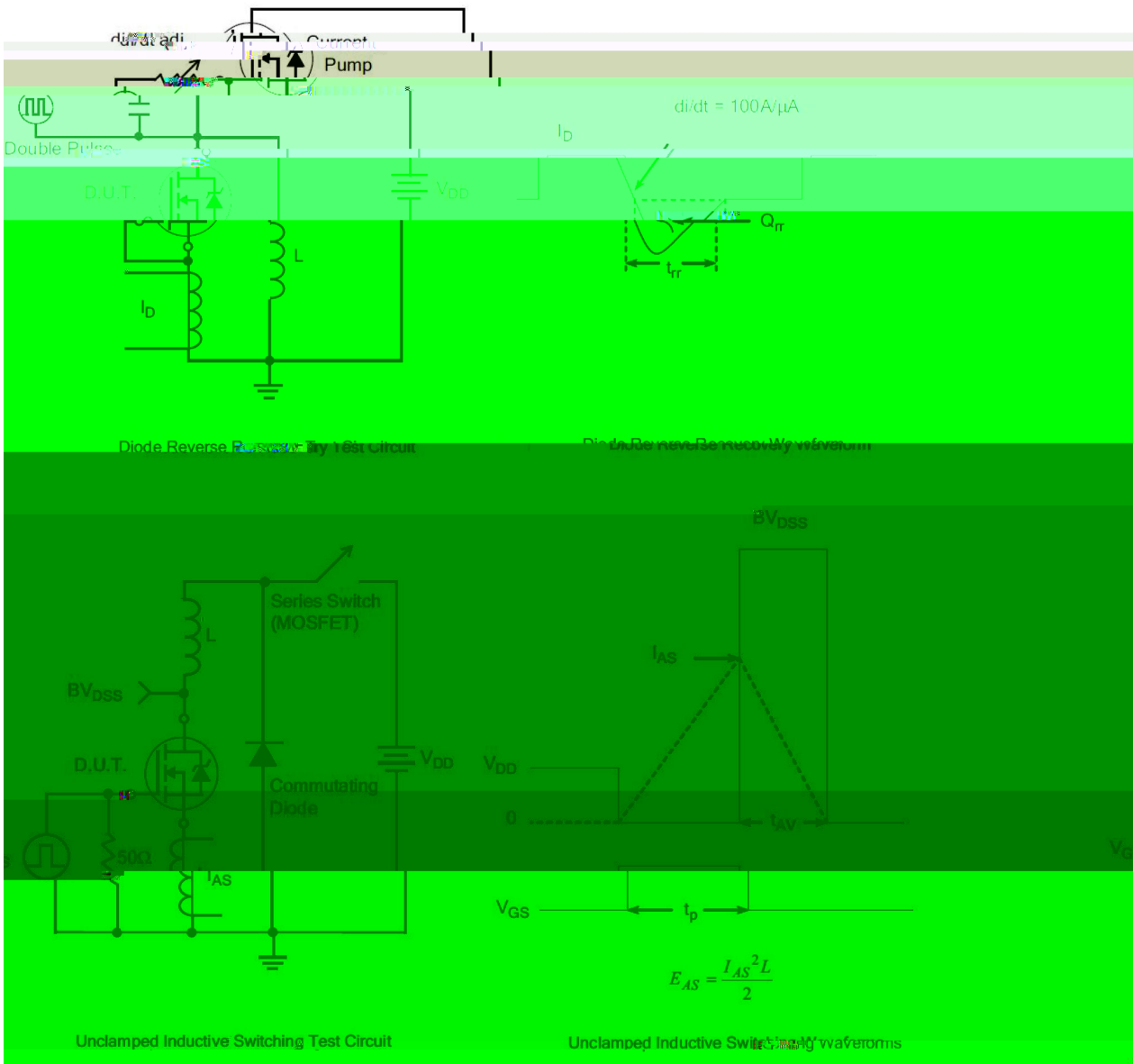
Gate Charge Test Circuit



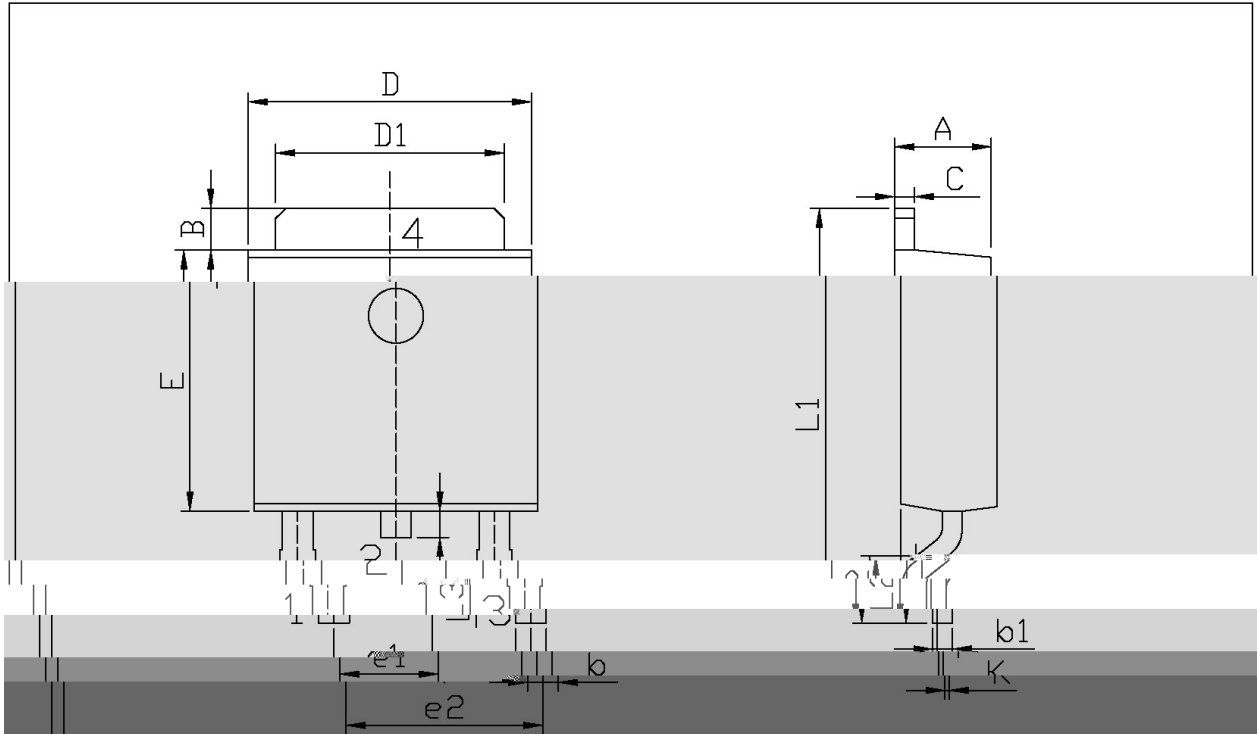
Gate Charge Waveform



/ Test Circuit and Waveform Curve



/ Package Dimensions



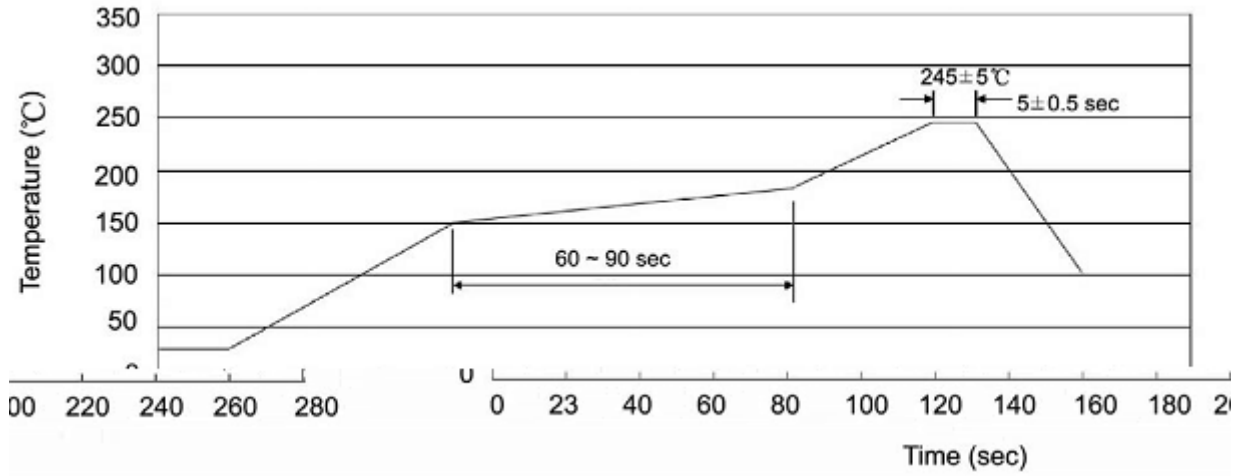
单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.70	e2	4.43	4.73
b1	0.45	0.55	L1	0.45	0.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

BRD640

() / Temperature Profile for Dip Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	只卷盘	卷盘盒	只盒	盒箱	只箱	盒	箱	

封装形式	包装数量					包装尺寸 :		
	只套管	套管盒	只盒	盒箱	只箱	套管	盒	箱

/ Notices